

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5527076

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
SEQUENCE:	2
CONVEYING PARTY DATA	
Name	Execution Date
SUNEDISON SEMICONDUCTOR LIMITED (UEN201334164H)	06/06/2018
RECEIVING PARTY DATA	
Name:	GLOBALWAFERS CO., LTD.
Street Address:	NO. 8 INDUSTRIAL EAST ROAD 2
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSINSHU
State/Country:	TAIWAN
Postal Code:	R.O.C.
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16414238
CORRESPONDENCE DATA	
Fax Number:	(314)612-2307
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	314-621-5070
Email:	USpatents@armstrongteasdale.com, clager@armstrongteasdale.com
Correspondent Name:	PATENT DOCKET DEPARTMENT ARMSTRONG TEASD
Address Line 1:	7700 FORSYTH BOULEVARD
Address Line 2:	SUITE 1800
Address Line 4:	ST. LOUIS, MISSOURI 63105
ATTORNEY DOCKET NUMBER:	28744-5005 (150078A.1)
NAME OF SUBMITTER:	MICHAEL G. MUNSELL
SIGNATURE:	/Michael G. Munsell/
DATE SIGNED:	05/16/2019
Total Attachments: 7	
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ASSIGNMENT

This Assignment is made by and among SunEdison Semiconductor Limited, a company organized and existing under the laws of Singapore ("SSL"), MEMC Japan Limited, a company organized and existing under the laws of Japan ("MEMC Japan"), and MEMC Electronic Materials, S.P.A., a company organized and existing under the laws of Italy ("MEMC EM", and collectively with SSL and MEMC Japan, the "Assignors"), and GlobalWafers Co., Ltd., a company organized and existing under the laws of Taiwan and having its registered address at No. 8, Industrial East Road, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C. (hereinafter referred to as "Assignee");

WHEREAS, on December 31, 2016, Assignors entered into certain IP Transfer Agreements with Assignee;

WHEREAS, the parties hereto desire to memorialize, *nunc pro tunc*, the assignment and ownership of all Assigned IP (defined below) for, among other things, recordal purposes with certain patent administration bodies, such as the United States Patent and Trademark Office; and

WHEREAS, Assignors acknowledge that payment in full from Assignee for all Assigned IP has heretofore been paid.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, Assignors have agreed to and do hereby sell, assign and transfer, and confirm the sale, assignment and transfer, unto Assignee all of their rights, title and interest throughout the world, including without limitation, the right to sue and recover for any past infringements, in and to the Listed IP, any other applications (including provisional, non-provisional, divisional, continuing, or reissue applications) based in whole or in part on any Listed IP, any corresponding patent or patent applications filed in any country based in whole or in part on, and/or claiming priority from, any Listed IP, any patents (including extensions thereof) of any country based in whole or in part on, and/or claiming priority from, any Listed IP, and all of the inventions described in the Listed IP and all of the aforementioned patents and patent applications (all of the foregoing, collectively, the "Assigned IP");

TO BE HELD AND ENJOYED by said Assignee, its successors and assigns, as fully and entirely as the Assigned IP would have been held and enjoyed by Assignors had no assignment of said interest been made.

EACH ASSIGNOR hereby agrees that it will do, execute and deliver, or will cause to be done, executed and delivered, all such further lawful acts, transfers, assignments and conveyances, powers of attorney and assurances for the better assuring, conveying and confirming unto Assignee, all of such Assignor's rights, title and interest in and to the Assigned IP hereby transferred, assigned and conveyed, as Assignee may reasonably require.

[Signature Pages Follow]

IN WITNESS WHEREOF, the undersigned have caused these presents to be executed by their respective officers thereunto duly authorized this 6 day of June, 2018.

Assignor:

SUNEDISON SEMICONDUCTOR LIMITED

By: *Paul Markowitz*

Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri
COUNTY OF St. Charles

On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of SUNEDISON SEMICONDUCTOR LIMITED, known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.

Erika Damiani
Notary Public

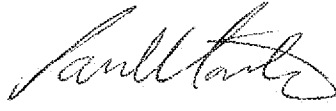
My Commission Expires:

July 20, 2018



Assignor:

MEMC JAPAN LTD

By: 


Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri
COUNTY OF St. Charles

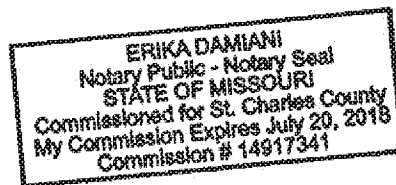
On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of MEMC JAPAN LTD, known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.


Notary Public

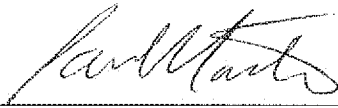
My Commission Expires:

July 20, 2018



Assignor:

MEMC ELECTRONIC MATERIALS S.P.A.

By: 


Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri
COUNTY OF St. Charles

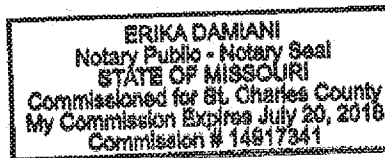
On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of MEMC ELECTRONIC MATERIALS S.P.A., known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.


Notary Public

My Commission Expires:

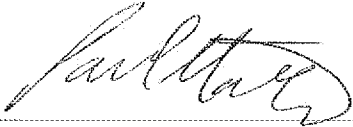
July 20, 2018



For and on behalf of GlobalWafers Co., Ltd.

Assignee:

GLOBALWAFERS CO., LTD.

By: 

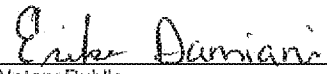
Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri)
COUNTY OF St. Charles

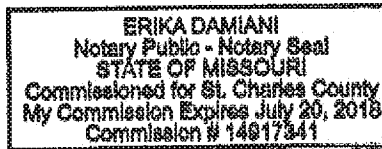
On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of GLOBALWAFERS CO., LTD., known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.


Notary Public

My Commission Expires:

July 20, 2018



SCHEDULE A

TITLE	Country	Application Number	Filing Date	Publication Number	Publication Date	Patent Number	Issue Date
MANUFACTURING METHOD OF SMOOTHING A SEMICONDUCTOR SURFACE	TW	107115498	8-May-2018				
MANUFACTURING METHOD OF SMOOTHING A SEMICONDUCTOR SURFACE	US	15/775924					
METHODS AND SYSTEM FOR CONTROLLING A SURFACE PROFILE OF A WAFER	US	15/247099	25-Aug-2016	2018-0056545	1-Mar-2018		
CRYSTAL PULLING SYSTEMS AND METHODS FOR PRODUCING MONOCRYSTALLINE INGOTS WITH REDUCED EDGE BAND DEFECTS	US	15/297853	19-Oct-2016	2017-0107639	20-Apr-2017		
CRYSTAL PULLING SYSTEM AND METHOD FOR INHIBITING PRECIPITATE BUILD-UP IN EXHAUST FLOW PATH	US	15/358589	22-Nov-2016	2017-0145587	25-May-2017		
THERMALLY STABLE CHARGE TRAPPING LAYER FOR USE IN MANUFACTURE OF SEMICONDUCTOR ON-INSULATOR STRUCTURES	US	15/557503	12-Sep-2017	2018-0047614	15-Feb-2018		
CRYSTAL PULLING SYSTEMS AND METHODS FOR PRODUCING MONOCRYSTALLINE INGOTS WITH REDUCED EDGE BAND DEFECTS	US	15/297853	19-Oct-2016	2017-0107639	20-Apr-2017		
PROCESS AND PLANT FOR THE PURIFICATION OF TRICHLOROSILANE AND SILICON TETRACHLORIDE	SG	201303855-9	17-May-2013	0191588	31-Jul-2013	0191588	22-Dec-2015
PROCESS AND PLANT FOR THE PURIFICATION OF TRICHLOROSILANE AND SILICON TETRACHLORIDE	TW	095106046	2-Mar-2006	1472486	11-Feb-2015	1472486	11-Feb-2015
PROCESS AND SYSTEM FOR THE PURIFICATION OF TRICHLOROSILANE AND SILICON TETRACHLORIDE	US	13/014532	26-Jan-2011	2011-0114469	19-May-2011	8282792	9-Oct-2012
PROCESSES FOR THE PURIFICATION OF TRICHLOROSILANE OR SILICON TETRACHLORIDE	US	13/606953	7-Sep-2012	2012-0325645	27-Dec-2012	8691055	8-Apr-2014
PROCESS AND PLANT FOR THE PURIFICATION OF TRICHLOROSILANE AND SILICON TETRACHLORIDE	DE	05813212.7	19-May-2007	1812343	1-Aug-2007	602005049326.3-08	11-May-2016
PROCESS AND PLANT FOR THE PURIFICATION OF TRICHLOROSILANE AND SILICON TETRACHLORIDE	KR	10-2007-7013735	18-Jun-2007			10-0981813	6-Sep-2010
PROCESS AND PLANT FOR THE PURIFICATION OF TRICHLOROSILANE AND SILICON TETRACHLORIDE	RU	2007122758	18-Jun-2007			2393991	10-Jul-2010

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